

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	("5736074"   "6114187"). PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:05
S2	766	264/401.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:59
S3	7	("20040036200"   "20040099983"   "20040145088"   "20040207123"   "20050012247"   "6572807"   "7120512"). PN. OR ("7329379").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 15:47
S4	178591	(fluid or solvent or resin or polymer or (metal near4 paste)) near7 (eject\$4 or dropping or deposit\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S5	3793762	(substrate or wafer or pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S6	83637	S4 and S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S7	3139993	(voltage or charge or (electric near4 field) or (electrostatic))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:54

S8	37057	S6 and S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:54
S9	1161081	(nozzle or printhead or ink \$4jet\$4 or stereolithograph \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S10	12179	S8 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S11	157	(solidifying) near5 (S4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S12	0	246/401.ccls. and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:56
S13	314	425/174.2.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:57
S14	20602	(freeform near4 fabrication) (stereolithography) (rapid near3 prototyping) (solid near2 fabrication) (solid near2 lithography) (((three near3 dimensional) or 3D) near5 (print\$3 or ink \$4print))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:43
S15	532063	(solid\$4 near5 (drop\$3 or material or resin))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44

S16	4265	S14 and S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44
S17	349	264/401.ccls. and S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44
S18	81675	(stack\$4) near6 (droplet or material)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:58
S19	26	S17 and S18	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:58
S20	11	voltage and S19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:02
S21	2	(nozzle or ink\$4head or ink\$4print ) and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:03
S22	10	fluid and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:05
S23	41	("4575330"   "4752352"   "4863538"   "4999143"   "5015312"   "5058988"   "5059021"   "5076974"   "5104592"   "5121329"   "5123734"   "5133987"   "5141680"   "5143663"   "5174931"   "5182056"   "5182715"   "5184307"   "5192469"   "5192559"   "5204055"   "5209878"   "5234636"   "5238639"   "5256340"   "5321622"	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 17:05

		"5597520"   "5840239"   "5902537"   "5902538"   "5943235"   "5945058"   "5965079"   "5999184"   "6001297").PN. OR ("6126884").URPN.				
S24	20086	264/401.ccls. (depositing and stacking)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S25	919	S14 and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S26	246	(solidifying) and S25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S27	766	264/401.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:27
S28	3793762	substrate or wafer or pad	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:27
S29	4999418	AC or DC or (direct near3 curent) or (alternating near3 current) or voltage or electrostatic or (electric near3 field) or (charge)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29
S30	66	S27 and S28 and S29	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29
S31	28	(droplet or solder) and S30	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29

S33	173792	((substrate or wafer or pad ) near2 heat\$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:30
S34	3	S31 and S33	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:31

**7/ 2/ 2009 2:33:37 PM****C:\ Documents and Settings\ nsultana\ My Documents\ EAST\ Workspaces\ 10566476.wsp**